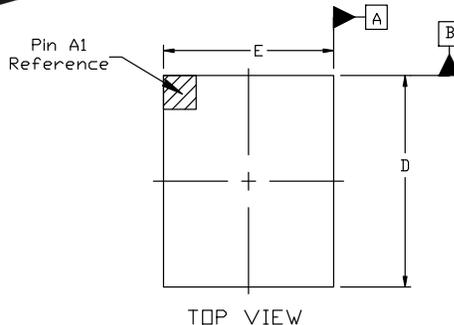
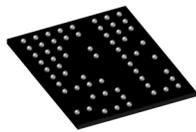


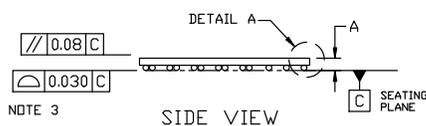
WLCSP62 3.004x2.419
CASE 567KQ
ISSUE O

DATE 06 MAR 2023



NOTES:

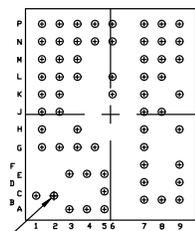
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.



NOTE 3

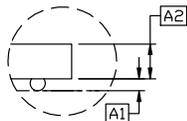
TOP VIEW

SIDE VIEW



BOTTOM VIEW

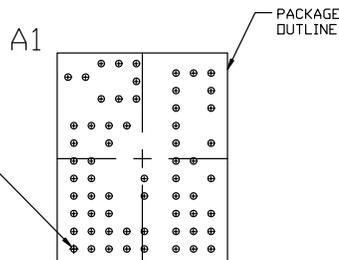
62X ϕ b
0.030 C A B
0.015 C



DETAIL A
SCALE 3:1

BALL POSITION TABLE (MM)					
CENTER OF DIE TO CENTER OF BALL/PAD			CENTER OF DIE TO CENTER OF BALL/PAD		
BALL	X	Y	BALL	X	Y
A3	-0.588	-1.348	K6	0.025	0.284
A4	-0.338	-1.348	K7	0.475	0.284
A5	-0.088	-1.348	K9	0.975	0.284
B7	0.475	-1.216	L1	-0.975	0.534
B8	0.725	-1.216	L2	-0.725	0.534
B9	0.975	-1.216	L3	-0.475	0.534
C1	-1.058	-1.158	L6	0.025	0.534
C2	-0.808	-1.158	L7	0.475	0.534
C5	-0.088	-1.098	L8	0.725	0.534
D7	0.475	-0.966	M1	-0.975	0.784
D9	0.975	-0.966	M2	-0.725	0.784
E3	-0.588	-0.848	M3	-0.475	0.784
E4	-0.338	-0.848	M7	0.475	0.784
E5	-0.088	-0.848	M8	0.725	0.784
F7	0.475	-0.716	M9	0.975	0.784
F9	0.975	-0.716	N1	-0.975	1.034
G1	-0.975	-0.466	N2	-0.725	1.034
G2	-0.725	-0.466	N3	-0.475	1.034
G3	-0.475	-0.466	N4	-0.225	1.034
G4	-0.225	-0.466	N6	0.025	1.034
G7	0.475	-0.466	N7	0.475	1.034
H1	-0.975	-0.216	N8	0.725	1.034
H3	-0.475	-0.216	N9	0.975	1.034
H7	0.475	-0.216	P1	-0.975	1.284
H9	0.975	-0.216	P2	-0.725	1.284
J1	-0.975	0.034	P3	-0.475	1.284
J2	-0.725	0.034	P4	-0.225	1.284
J7	0.475	0.034	P6	0.025	1.284
J8	0.725	0.034	P7	0.475	1.284
K1	-0.975	0.284	P8	0.725	1.284
K2	-0.725	0.284	P9	0.975	1.284

MOUNTING PAD POSITION TABLE (MM)					
CENTER OF DIE TO CENTER OF BALL/PAD			CENTER OF DIE TO CENTER OF BALL/PAD		
BALL	X	Y	BALL	X	Y
A3	-0.588	1.348	K6	0.025	-0.284
A4	-0.338	1.348	K7	0.475	-0.284
A5	-0.088	1.348	K9	0.975	-0.284
B7	0.475	1.216	L1	-0.975	-0.534
B8	0.725	1.216	L2	-0.725	-0.534
B9	0.975	1.216	L3	-0.475	-0.534
C1	-1.058	1.158	L6	0.025	-0.534
C2	-0.808	1.158	L7	0.475	-0.534
C5	-0.088	1.098	L8	0.725	-0.534
D7	0.475	0.966	M1	-0.975	-0.784
D9	0.975	0.966	M2	-0.725	-0.784
E3	-0.588	0.848	M3	-0.475	-0.784
E4	-0.338	0.848	M7	0.475	-0.784
E5	-0.088	0.848	M8	0.725	-0.784
F7	0.475	0.716	M9	0.975	-0.784
F9	0.975	0.716	N1	-0.975	-1.034
G1	-0.975	0.466	N2	-0.725	-1.034
G2	-0.725	0.466	N3	-0.475	-1.034
G3	-0.475	0.466	N4	-0.225	-1.034
G4	-0.225	0.466	N6	0.025	-1.034
G7	0.475	0.466	N7	0.475	-1.034
H1	-0.975	0.216	N8	0.725	-1.034
H3	-0.475	0.216	N9	0.975	-1.034
H7	0.475	0.216	P1	-0.975	-1.284
H9	0.975	0.216	P2	-0.725	-1.284
J1	-0.975	-0.034	P3	-0.475	-1.284
J2	-0.725	-0.034	P4	-0.225	-1.284
J7	0.475	-0.034	P6	0.025	-1.284
J8	0.725	-0.034	P7	0.475	-1.284
K1	-0.975	-0.284	P8	0.725	-1.284
K2	-0.725	-0.284	P9	0.975	-1.284



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SLDERRM/D.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.150	0.175	0.200
A1	0.060	0.075	0.090
A2	0.087	0.100	0.113
b	0.087	0.102	0.117
D	2.979	3.004	3.029
E	2.394	2.419	2.444

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